# Abstracts

## An advanced hybrid assembly technique for 40 Gbit/s-modules including surface and feed-through capacitors

*G. Hanke, W. Nohr and D. Weber. "An advanced hybrid assembly technique for 40 Gbit/s-modules including surface and feed-through capacitors." 1998 MTT-S International Microwave Symposium Digest 98.3 (1998 Vol. III [MWSYM]): 1703-1706.*

Experimental 40 Gbit/s ETDM transmitter and receiver modules for optical fiberlink applications were developed. To obtain the essential extreme broad bandwidth the GaAs-chips are connected by self-supporting leads to ceramic thin film circuits which shows nearly reflection- and discontinuity-free connections up to millimeter-wave frequencies. In addition the use of hybrid integrated surface and coaxial feed-through capacitors results in low impedances and ultra broadband bypasses.

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